

ABSTRACT OF THE DISCLOSURE

A solder ball mounting device for mounting solder balls on a workpiece is disclosed. A solder ball supplying section in which the solder balls are stored; a sucking head having a plurality of solder ball sucking holes in a lower surface thereof; sucking means coupled to the sucking head so as to suck the solder balls in the solder ball sucking holes; lift means for vertically moving the sucking head; and pressure adjusting means for adjusting and setting degree of vacuum in the sucking head to a first pressure for sucking the solder balls, and to a second pressure which is lower in the degree of vacuum than the first pressure and is high enough to hold the solder balls sucked, are provided. When the sucking head is positioned at a lower position where the sucking head sucks the solder balls by means of the lift means, the pressure adjusting means adjusts and sets the degree of vacuum in the sucking head to the first pressure, and when the degree of vacuum in the sucking head reaches the first pressure, the lift means moves the sucking head upwardly, and thereafter the pressure adjusting means starts adjusting the degree of vacuum in the sucking head thereby setting to the second pressure.

